

PHP47NQ10T; PHB47NQ10T

N-channel enhancement mode field-effect transistor

Rev. 01 — 16 May 2001

Product data

1. Description

N-channel enhancement mode field-effect power transistor in a plastic package using TrenchMOS™¹ technology.

Product availability:

PHP47NQ10T in SOT78 (TO-220AB)

PHB47NQ10T in SOT404 (D²-PAK).

2. Features

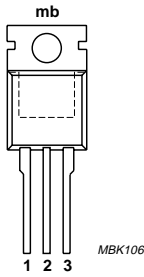
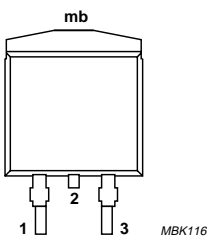
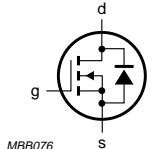
- Fast switching
- Very low on-state resistance.

3. Applications

- DC to DC converters
- Switched mode power supplies.

4. Pinning information

Table 1: Pinning - SOT78 and SOT404, simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)	 SOT78 (TO-220AB)	 SOT404 (D ² -PAK)
2	drain (d) [1]		
3	source (s)		
mb	mounting base; connected to drain (d)		
		 MBB076	

[1] It is not possible to make connection to pin 2 of the SOT404 package.

1. TrenchMOS is a trademark of Royal Philips Electronics.



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5. Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 175 °C	–	100	V
I_D	drain current (DC)	$T_{mb} = 25$ °C; $V_{GS} = 10$ V	–	47	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C	–	166	W
T_j	junction temperature		–	175	°C
$R_{DS(on)}$	drain-source on-state resistance	$T_j = 25$ °C; $V_{GS} = 10$ V; $I_D = 25$ A	20	28	mΩ

6. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

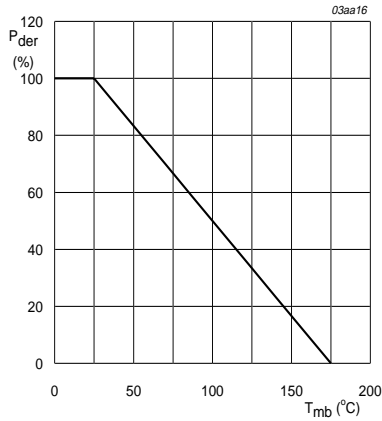
Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 175 °C	–	100	V
V_{DGR}	drain-gate voltage (DC)	$T_j = 25$ to 175 °C; $R_{GS} = 20$ kΩ	–	100	V
V_{GS}	gate-source voltage (DC)		–	±20	V
I_D	drain current (DC)	$T_{mb} = 25$ °C; $V_{GS} = 10$ V Figure 2 and 3	–	47	A
		$T_{mb} = 100$ °C; $V_{GS} = 10$ V Figure 2	–	33	A
I_{DM}	peak drain current	$T_{mb} = 25$ °C; pulsed; $t_p \leq 10$ μs; Figure 3	–	187	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C; Figure 1	–	166	W
T_{stg}	storage temperature		–55	175	°C
T_j	operating junction temperature		–55	175	°C

Source-drain diode

I_S	source (diode forward) current (DC)	$T_{mb} = 25$ °C	–	47	A
I_{SM}	peak source (diode forward) current	$T_{mb} = 25$ °C; pulsed; $t_p \leq 10$ μs	–	187	A

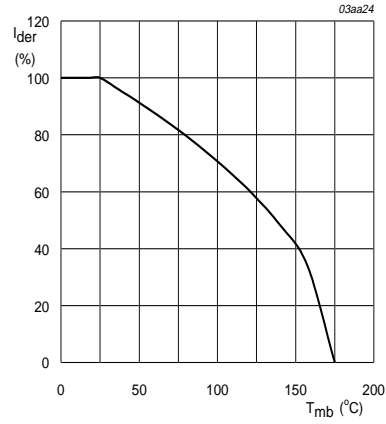
Avalanche ruggedness

E_{AS}	non-repetitive avalanche energy	unclamped inductive load; $I_{AS} = 30$ A; $t_p = 0.1$ ms; $V_{DD} \leq 25$ V; $R_{GS} = 50$ Ω; $V_{GS} = 5$ V; starting $T_j = 25$ °C; Figure 4	–	45	mJ
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$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

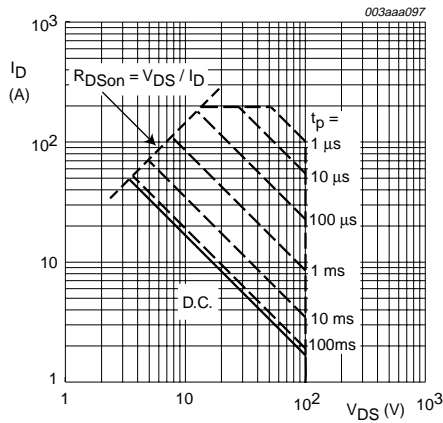
Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$V_{GS} \geq 10 \text{ V}$$

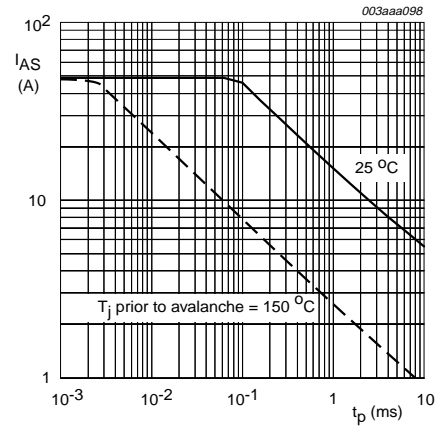
$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



$T_{mb} = 25^{\circ}C$; I_{DM} is single pulse.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.



Unclamped inductive load; $V_{DD} \leq 25 \text{ V}$; $R_{GS} = 50 \Omega$; $V_{GS} = 5 \text{ V}$; starting $T_j = 25^{\circ}C$ and $150^{\circ}C$.

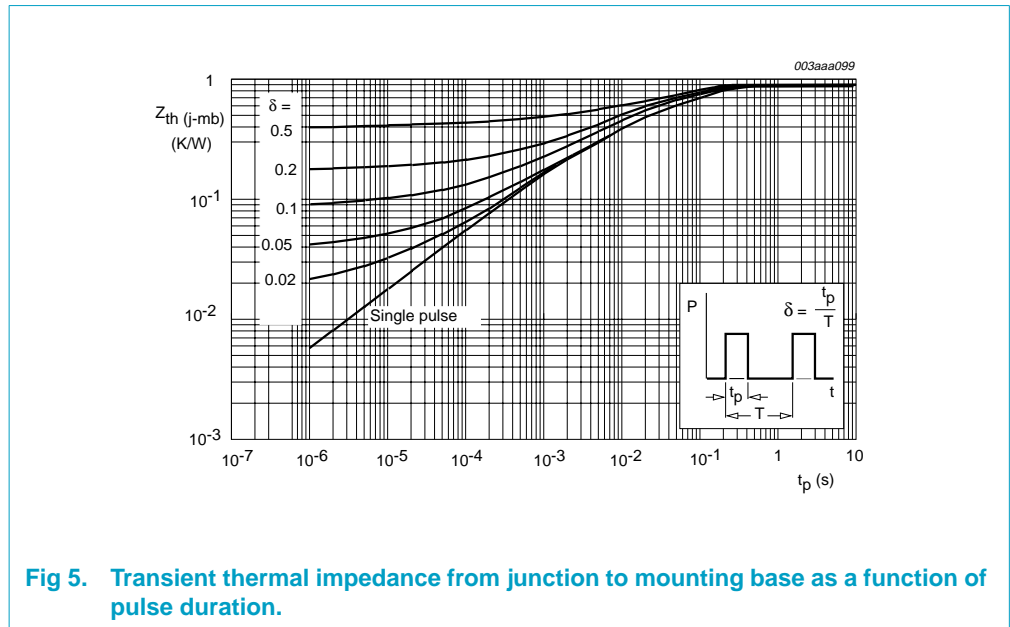
Fig 4. Non-repetitive avalanche ruggedness current as a function of pulse duration.

7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Figure 5	0.9	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	SOT78 package; vertical in still air.	60	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	SOT404 package; mounted on printed circuit board; minimum footprint.	50	K/W

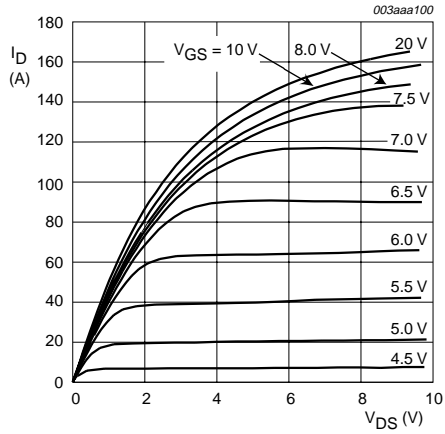
7.1 Transient thermal impedance



8. Characteristics

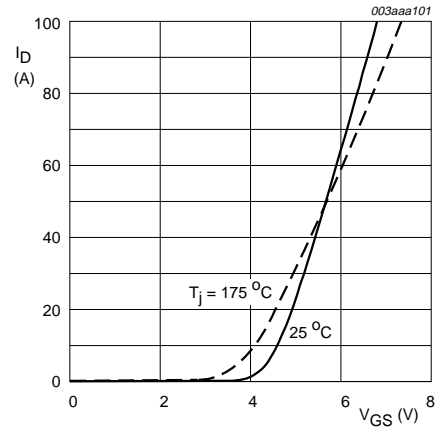
Table 5: Characteristics
 $T_j = 25\text{ °C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$; $V_{GS} = 0\ \text{V}$	100	–	–	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ \text{mA}$; $V_{DS} = V_{GS}$; Figure 10				
		$T_j = 25\text{ °C}$	2	3	4	V
		$T_j = 175\text{ °C}$	1	–	–	V
I_{DSS}	drain-source leakage current	$V_{GS} = 0\ \text{V}$; $V_{DS} = 100\ \text{V}$				
		$T_j = 25\text{ °C}$	–	0.05	10	μA
		$T_j = 175\text{ °C}$	–	–	500	μA
I_{GSS}	gate-source leakage current	$V_{DS} = 0\ \text{V}$; $V_{GS} = \pm 20\ \text{V}$	–	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}$; $I_D = 25\ \text{A}$; Figure 8 and 9				
		$T_j = 25\text{ °C}$	–	20	28	m Ω
		$T_j = 175\text{ °C}$	–	–	76	m Ω
Dynamic characteristics						
$Q_{g(tot)}$	total gate charge	$I_D = 40\ \text{A}$; $V_{DD} = 80\ \text{V}$;	–	66	–	nC
Q_{gs}	gate-source charge	$V_{GS} = 10\ \text{V}$; Figure 15	–	12	–	nC
Q_{gd}	gate-drain (Miller) charge		–	21	–	nC
C_{iss}	input capacitance	$V_{GS} = 0\ \text{V}$; $V_{DS} = 25\ \text{V}$;	–	2320	3100	pF
C_{oss}	output capacitance	$f = 1\ \text{MHz}$; Figure 13	–	315	378	pF
C_{rss}	reverse transfer capacitance		–	187	256	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 30\ \text{V}$; $R_D = 1.2\ \Omega$;	–	15	23	ns
t_r	rise time	$V_{GS} = 10\ \text{V}$; $R_G = 10\ \Omega$	–	70	105	ns
$t_{d(off)}$	turn-off delay time		–	83	116	ns
t_f	fall time		–	45	63	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 25\ \text{A}$; $V_{GS} = 0\ \text{V}$; Figure 14	–	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 47\ \text{A}$;	–	66	–	ns
Q_r	recovered charge	$dI_S/dt = -100\ \text{A}/\mu\text{s}$; $V_{GS} = -10\ \text{V}$; $V_R = 30\ \text{V}$	–	0.24	–	μC



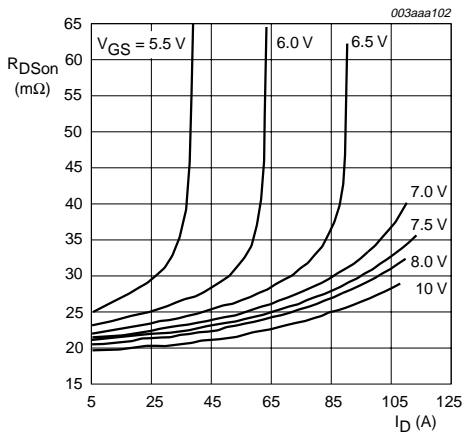
$T_j = 25\text{ }^\circ\text{C}$

Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values.



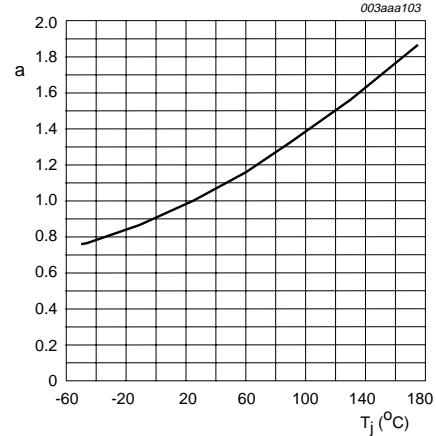
$T_j = 25\text{ }^\circ\text{C}$ and 175 °C; $V_{DS} > I_D \times R_{DSon}$

Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



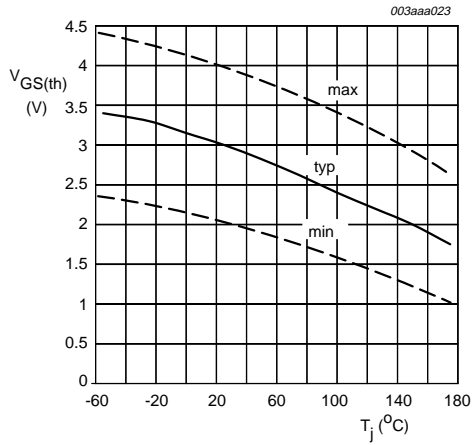
$T_j = 25\text{ }^\circ\text{C}$

Fig 8. Drain-source on-state resistance as a function of drain current; typical values.



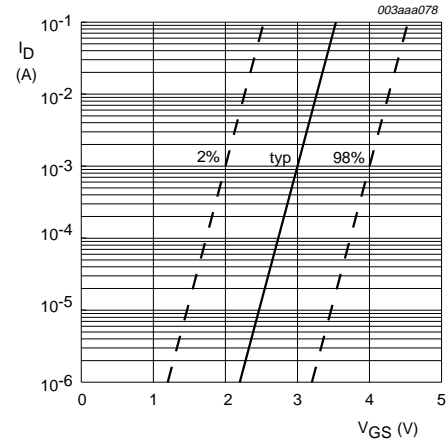
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 9. Normalized drain-source on-state resistance factor as a function of junction temperature.



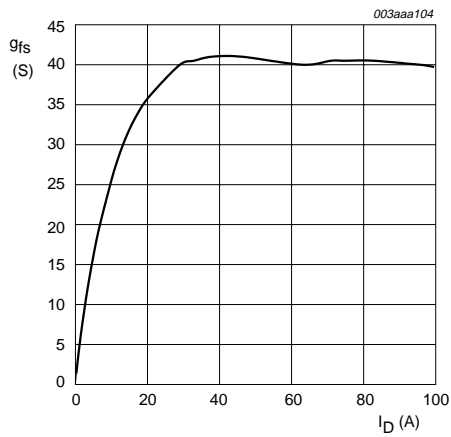
$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$

Fig 10. Gate-source threshold voltage as a function of junction temperature.



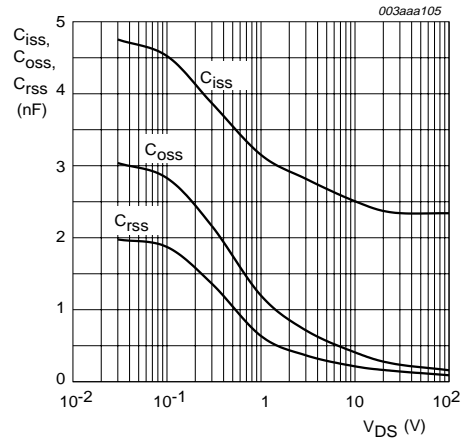
$T_j = 25 \text{ }^{\circ}C$

Fig 11. Sub-threshold drain current as a function of gate-source voltage.



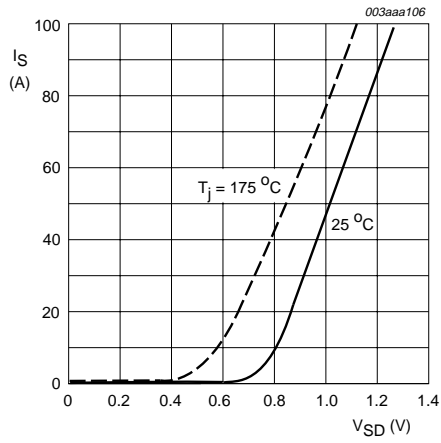
$T_j = 25 \text{ }^{\circ}C$; $V_{DS} = 25 \text{ V}$

Fig 12. Forward transconductance as a function of drain current; typical values.



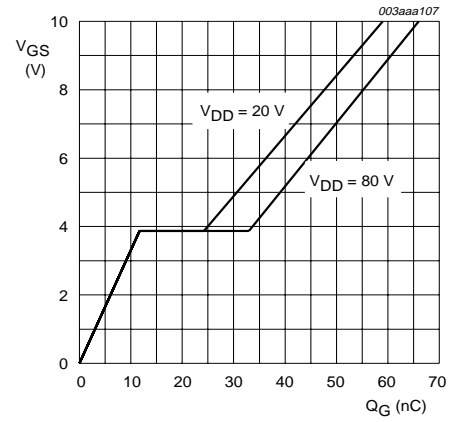
$V_{GS} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25^\circ\text{C}$ and 175°C ; $V_{GS} = 0\text{ V}$

Fig 14. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



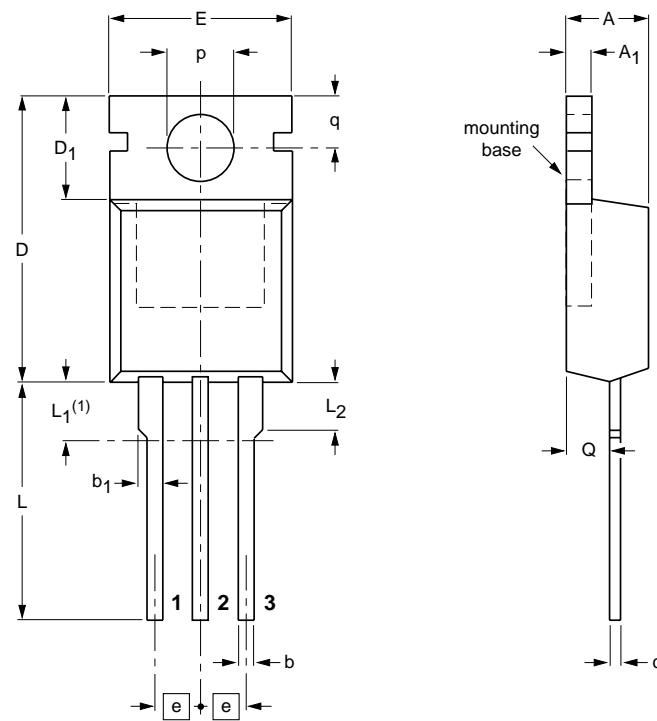
$I_D = 40\text{ A}$; $V_{DD} = 20\text{ V}$ and 80 V

Fig 15. Gate-source voltage as a function of gate charge; typical values.

9. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁	c	D	D ₁	E	e	L	L ₁ ⁽¹⁾	L ₂ max.	p	q	Q
mm	4.5	1.39	0.9	1.3	0.7	15.8	6.4	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.27	0.7	1.0	0.4	15.2	5.9	9.7		13.5	2.79		3.6	2.7	2.2

Note

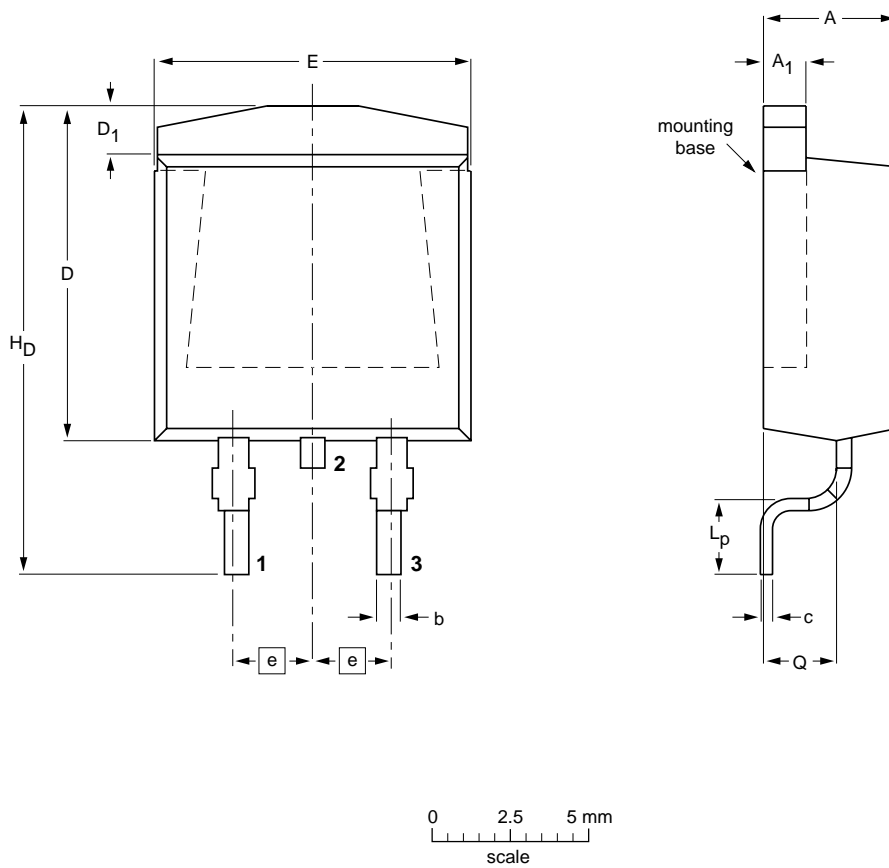
1. Terminals in this zone are not tinned.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT78		3-lead TO-220AB	SC-46			00-09-07- 01-02-16

Fig 16. SOT78 (TO-220AB)

Plastic single-ended surface mounted package (Philips version of D²-PAK); 3 leads
(one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	c	D max.	D ₁	E	e	L _p	H _D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT404					99-06-25 01-02-12

Fig 17. SOT404 (D²-PAK).

10. Revision history

Table 6: Revision history

Rev	Date	PCPN	Description
01	20010516	-	Product data. Initial version.

11. Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definition
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

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